### PRELIMINARY

# NearStack High-Speed Connector System and Cable Jumper Assemblies **molex**

NearStack High-Speed Connector System and Cable Jumper Assemblies use twinax cables to deliver a PCB alternative with superior signal integrity and low insertion loss while enabling implementation of 56 Gbps NRZ and a path to 112 Gbps PAM-4

### **Features and Benefits**

0.60mm pitch and tight stacking on 9.00-by-19.00 grid (high density with 30.2 differential pairs per square inch)Alleviates space constraints by taking up less PCB real estate

Capable of 112 Gbps PAM-4 protocol Offers cutting-edge performance



Minimum length: 150.00mm: maximum length: 1.5m. Custom lengths available Provides design flexibility



NearStack-to-NearStack Cable Jumper Assembly



Larger circuit sizes: up to 6 by 7 (42 differential pairs) Reduces PCB real estate. Increases density

### Assemblies are 100 percent tested

Delivers a reliable cable assembly. Eliminates the need for the customer to conduct tests



### More direct links and lower loss with twinax cables vs. PCB traces

Takes high-speed signals to NearStack Connector. Achieves superior signal integrity channel performance. Allows for fewer layers of PCB material for greater cost effectiveness. Enables shorter channels compared with PCB traces



**NearStack Cable** Assemblies available with other Molex connectors at opposite end (e.g., NearStack to Impulse, Impel, zQSFP+ and zQSFP DD **Connectors**) Delivers versatile I/O, backplane solutions



NearStack-to-Impulse Cable Jumper Assemblies



NearStack Mated Connector Set



of 100.00mm

Larger circuit sizes: up to 6 wafers by 7 DPs (42 DPs total); 2 wafers by 4 DPs (8 DPs total) currently tooled with a roadmap up to 6 wafers and a mixed 10-SE/4-DP wafer

Reduces PCB real estate. Offers high density

Mated NearStack Connector System, 8 Differential Pairs

## NearStack High-Speed Connector System and Cable Jumper Assemblies **molex**

### **Features and Benefits**



### **Data Centers**

Switches

### Specifications

### **REFERENCE INFORMATION**

Designed In: Millimeters RoHS: Yes Halogen Free: Yes

### ELECTRICAL

Voltage (max.): 30V RMS Current (max.): 0.5A Contact Resistance: 20 milliohms Dielectric Withstanding Voltage: 200V AC RMS Insulation Resistance: 1000 Megohms

Note: Molex reserves the right to delay or cancel production of the depicted product without additional notice. Please contact your Molex customer service representative for product availability.

### MECHANICAL Mating Force: TBD

connectors to be placed around the ASIC

Mating Force: TBD Unmating Force: 30N Durability (min.): 100 Cycles

### PHYSICAL

Provides additional

strain relief

Housing: LCP Contact: Copper (Cu) Plating: Contact Area — 0.76µ (30µ") Compliant Pin Area — Selective Tin (Sn) over 1.27µ (50µ") Nickel (Ni) Overall Operating Temperature: -55 to +105°C

### www.molex.com/link/nearstack.html

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locks the receptacle latches to

prevent unplugging until bale

is pulled